

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

QFN 4mm X 4mm Exp. Pad

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**TOTAL MASS (g) : 0.040553**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001686	1000000	41575.7265625		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.015961	975000	393588.46875		
		Iron (Fe)	7439-89-6	0.000393	24000	9691.13867188		
		Phosphorus (P)	7723-14-0	0.000005	300	123.296936035		
		Zinc (Zn)	7440-66-6	0.000011	700	271.253265381		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.016370</b>	<b>1000000</b>	<b>403674.1875</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000773	1000000	19049.5527344		
		<b>External Plating Total:</b>				<b>0.000773</b>	<b>1000000</b>	<b>19049.5527344</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000362	1000000	8926.69824219		
<b>Internal Plating Total:</b>				<b>0.000362</b>	<b>1000000</b>	<b>8926.69824219</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000811	750000	19998.7636719		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000270	250000	6658.03417969		
<b>Die Attach Total:</b>				<b>0.001081</b>	<b>1000000</b>	<b>26656.796875</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.002616	130000	64508.953125		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.017303	860000	426681.375		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000201	10000	4956.53710938		
		<b>Encapsulation Total:</b>				<b>0.020120</b>	<b>1000000</b>	<b>496146.875</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000161	1000000	3970.16162109		
					<b>TOTAL MASS (g) :</b>	<b>0.040553</b>		